

FlipChip International Appoints Jay Grover as Chief Operating Officer

PHOENIX, Arizona, June 27, 2006---FlipChip International LLC announced today that it has appointed Jay Grover as Chief Operating Officer for its semiconductor wafer scale packaging and bumping business in Phoenix, Arizona. Jay Grover joined FCI in 2005 as its Vice President of Operations and will be responsible in his new position for FCI's turn-key manufacturing services and logistics ranging from its advanced bumping fab to its back-end semiconductor services including dicing, tape & reel, wafer thinning and test operations. Jay has an extensive background in advanced manufacturing systems and has managed successful operations in multiple facilities in his 22 year career in manufacturing.

Bob Forcier, President and CEO of FlipChip International, stated, "Jay's proven track record in continuous improvement of our high quality standards, customer service and lean manufacturing initiatives is a testimonial to his capabilities and leadership skills. We are also very excited to have Jay lead our aggressive expansion in wafer processing capacity of 118% in 2006 and 2007. Customer demand has been strong under Jay's leadership and we will continue to build our capabilities with Jay directing our operations and logistic teams. Under Jay's leadership, our investments in advanced manufacturing technologies such as cell control, capacity planning, CIM, and ERP will pay many dividends to our customer service."

FlipChip International, LLC is privately held supplier of products and services for the wafer bumping and wafer scale packaging semiconductor market. Flip Chip International, LLC is a wholly owned subsidiary of RoseStreet Labs LLC, a supplier of products and services for wireless infrastructure in the life science, renewable energy and homeland security markets.

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